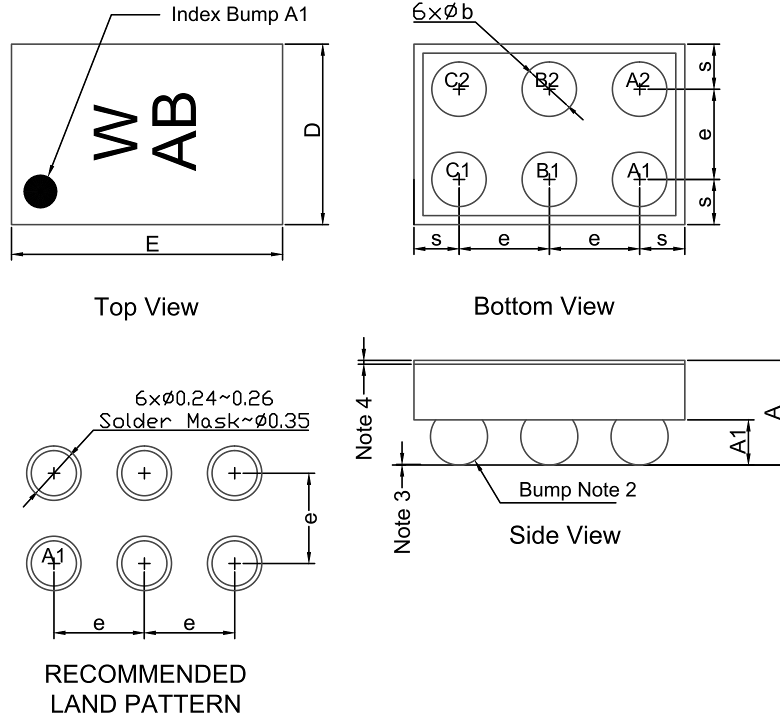
WCSP6: 6 Bumps

(2 x 3, 0.5 mm pitch, 250 µm bump height, 1 mm x 1.5 mm die size)



DIMENSION	MILLIMETERS [5]			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.540	0.572	0.620	0.0212	0.0225	0.0244
A1	0.214	0.250	0.286	0.0084	0.0098	0.0113
b	0.279	0.310	0.372	0.0109	0.0122	0.0146
e		0.500			0.0197	
s	0.230	0.250	0.270	0.0090	0.0098	0.0106
D	0.920	0.960	1.000	0.0362	0.0378	0.0394
E	1.420	1.460	1.500	0.0559	0.0575	0.0591

Notes (unless otherwise specified)
[1] Laser mark on the silicon die back coated with an epoxy film.
[2] Bumps are SAC396.
[3] 0.050 max. co-planarity.
[4] Laminate tape thickness is 0.022 mm.
[5] Use millimeters as the primary measurement.

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For technical questions, contact: powerictechsupport@vishay.com
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